Transistors with built-in Resistor

UNR32AE

Silicon NPN epitaxial planar type

For digital circuits

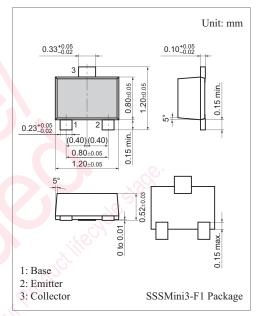
Features

- Suitable for high-density mounting and downsizing of the equipment
- Contribute to low power consumption

Absolute Maximum Ratings $T_a = 25^{\circ}C$

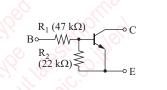
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	50	V	
Collector-emitter voltage (Base open)	V _{CEO}	50	V	
Collector current	I _C	80	mA	
Total power dissipation	P _T	100	mW	
Junction temperature	Tj	125	°C	
Storage temperature	T _{stg}	-55 to +125	°C	



Marking Symbol: KC

Internal Connection



Тур

Max

0.1

0.5

Unit

V

V

μΑ

μΑ

Conditions Parameter Symbol Min 50 Collector-base voltage (Emitter open) $I_{\rm C} = 10 \ \mu A$, $I_{\rm E} = 0$ V_{CBO} Collector-emitter voltage (Base open) $I_{\rm C} = 2 \, {\rm mA}, I_{\rm B} = 0$ 50 V_{CEO} $V_{CB} = 50 \text{ V}, I_E = 0$ Collector-base cutoff current (Emitter open) I_{CBO} Collector-emitter cutoff current (Base open) $V_{CE} = 50 \text{ V}, I_B = 0$ I_{CEO}

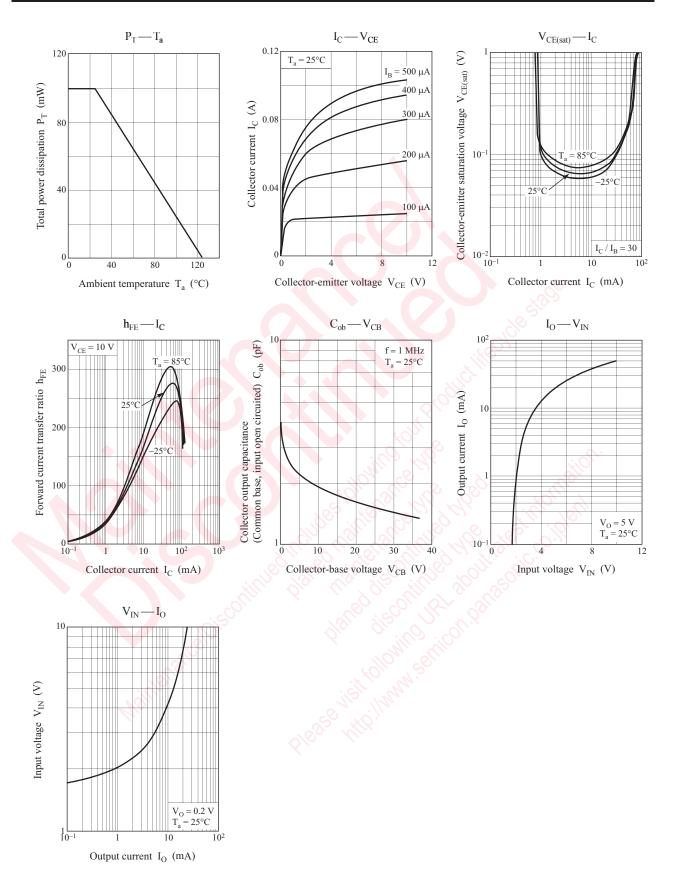
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{\rm EB} = 6 \text{V}, \text{I}_{\rm C} = 0$			0.2	mA
Forward current transfer ratio	h _{FE}	$V_{CE} = 10 \text{ V}, I_{C} = 5 \text{ mA}$	60			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 10 \text{ mA}, I_{\rm B} = 0.3 \text{ mA}$			0.25	V
Output voltage high-level	V _{OH}	$V_{\rm CC}$ = 5 V, $V_{\rm B}$ = 0.5 V, $R_{\rm L}$ = 1 k Ω	4.9			V
Output voltage low-level	V _{OL}	$V_{CC} = 5 \text{ V}, V_{B} = 6 \text{ V}, R_{L} = 1 \text{ k}\Omega$			0.2	V
Input resistance	R ₁		-30%	47	+30%	kΩ
Resistance ratio	R_1 / R_2		1.7	2.1	2.6	
Transition frequency	f _T	$V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$		150		MHz

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

Publication date: November 2004

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Panasonic



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